



# Wiring, Printed - Component

**COMPANY**

**ELTEK LTD**  
 SEGULA INDUSTRIAL ZONE  
 PO BOX 159  
 PETACH-TIKVA, 49101 Israel

**E51098**

Type	Cond Width		Cond Thk	SS/DSO	Max Area Diam	Report date After 2022-01-01	Surface Mount Technology	Assembly Process Temp °C	Solder Process Cycles	Solder Limits °C sec	Max Oper Temp °C	Meets UL796 Flame Class	Meets DSR	C T
	Min mm	Edge mm												
<b>Multilayer printed wiring boards</b>														
<b>1</b>	0.10	0.30	34 Int:68	DS	31.75	No	-	-	-	260	20	105	V-0	All *
<b>1-1</b>	0.10	0.08	8.5 Int:68	DS	31.75	No	-	-	-	260	20	105	V-0	All 3
<b>2</b>	0.05	0.15	8.5 Int:68	DS	31.75	No	-	-	-	288	30	130	V-0	All 3
<b>3</b>	0.05	0.15	8.5 Int:68	DS	31.75	No	-	-	-	288	30	130	V-0	All 4
<b>4 (ASP 1)</b>	0.05	0.15	8.5 Int:68	DS	31.75	Yes	Yes	260	6	288	30	130	V-0	All 3
<b>Multilayer printed wiring boards made from prefabricated type (mass laminated) industrial laminates</b>														
<b>1</b>	0.10	0.3	33	DS	31.8	No	-	-	-	260	20	105	V-0	- -
<b>Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions, flammability only Recognition</b>														
<b>EK</b>	-	-	-	DS	-	No	-	-	-	288	30	-	V-0	- -
<b>EK1</b>	-	-	-	DS	-	No	-	-	-	288	30	-	V-0	- -
<b>Single layer printed wiring boards</b>														
<b>1A</b>	0.10	0.30	34	DS	31.75	No	-	-	-	260	20	105	V-0	All -
<b>1A-1</b>	0.10	0.08	8.5	DS	31.75	No	-	-	-	260	20	105	V-0	All -
<b>2A</b>	0.05	0.15	8.5	DS	31.75	No	-	-	-	288	30	130	V-0	All -
<b>3A</b>	0.05	0.15	8.5	DS	31.75	No	-	-	-	288	30	130	V-0	All -
<b>4A (ASP 1)</b>	0.05	0.15	8.5	DS	31.75	Yes	Yes	260	6	288	30	130	V-0	All 3

\* - CTI marking is optional and may be marked on the printed wiring board.

(ASP 1) - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or tradename "EK", "EL" or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

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